

22mΩ, 600V, Super Junction N-Channel Power MOSFET
SRC60R022FBS

General Description

The Sanrise SRC60R022FBS is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R022FBS break down voltage is 600V and it has a high rugged avalanche characteristics.

The SRC60R022FBS is available in TO-247 package.

Symbol

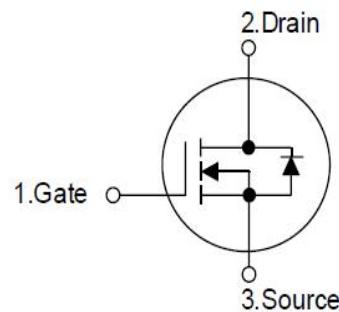
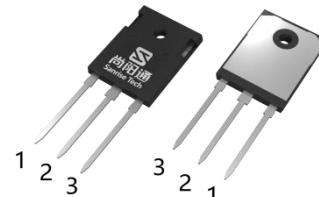


Figure 1 Symbol of SRC60R022FBS

Features

- Ultra Low $R_{DS(ON)}$ = 22mΩ @ V_{GS} = 10V.
- $V_{DS} @ T_{Jmax} = 650V$.
- Ultra Low Gate Charge, $Q_g = 168nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified
- Ultra-fast body diode

Package Type



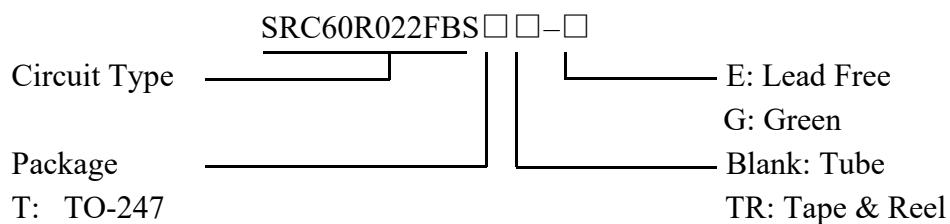
TO-247

Figure 2 Package Type of SRC60R022FBS

Application

- EV Charger
- Server / Telecom

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-247	SRC60R022FBST-G	SRC60R022FBSTG	Tube

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Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DSS}	600	V
Gate-Source Voltage	V _{GSS}	±30	V
Gate-Source Voltage (dynamic), AC (f>1 Hz)	V _{GSS}	±30	V
Power Dissipation(T _C =25°C, TO-247)	P _{tot}	595	W
Continuous Drain Current	T _C =25°C	115	A
	T _C =100°C	72.7	
	T _C =125°C	51.4	
Pulsed Drain Current (Note 2)	I _{DM}	345	A
Avalanche Energy, Single Pulse (Note 3)	E _{AS}	600	mJ
Avalanche Energy, Single Pulse (Note 4)	E _{AS}	3802	mJ
Avalanche Energy, Repetitive (Note 2)	E _{AR}	1.6	mJ
Avalanche Current, Repetitive (Note 2)	I _{AR}	7.8	A
Continuous Diode Forward Current	I _S	115	A
Diode Pulse Current	I _{S,PULSE}	345	A
MOSFET dv/dt Ruggedness, V _{DS} <=480V	dv/dt	80	V/ns
Reverse Diode dv/dt, V _{DS} <=480V, I _{SD} <=I _D	dv/dt	50	V/ns
Operating Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)	T _{LEAD}	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.
Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. I_{AS} = 7.8A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C. Finish goods test condition.
4. I_{AS} = 19.5A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C. Typical Eas.

Thermal characteristics

Parameter	Symbol	Package	Value (Max.)	Unit
Thermal resistance, junction - case	R _{thJC}	TO-247	0.21	°C /W
Thermal resistance, junction – ambient (Leaded)	R _{thJA}	TO-247	62	°C /W

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Electrical Characteristics

T_J = 25 °C, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	600			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =600V, V _{GS} =0V			10	uA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} =30V, V _{DS} =0V		200	nA
	Reverse	I _{GSSR}	V _{GS} =-30V, V _{DS} =0V		-200	
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =3.0mA	3.0	4.0	5.0	V
Static Drain-Source On-Resistance	R _{DSS(ON)}	V _{GS} =10V, I _D =57A		18.6	22	mΩ
Gate Resistance	R _G	f=1MHz, Open Drain		1.6		Ω
Dynamic Characteristics						
Input Capacitance	C _{ISS}	V _{DS} =400V, V _{GS} =0V, f=100KHz		10.3		nF
Output Capacitance	C _{OSS}			206		pF
Effective output capacitance, energy related <small>NOTE5</small>	C _{O(er)}	V _{GS} =0V, V _{DS} =0...400V		301.4		pF
Effective output capacitance, time related <small>NOTE6</small>	C _{O(tr)}			1835.7		
Turn-on Delay Time	t _{d(on)}	V _{DD} =400V, I _D =57A R _G =1.8Ω, V _{GS} =10V		29		ns
Rise Time	t _r			26		
Turn-off Delay Time	t _{d(off)}			74		
Fall Time	t _f			6		
Gate Charge Characteristics						
Gate to Source Charge	Q _{gs}	V _{DD} =480V, I _D =57A V _{GS} =0 to 10V		78		nC
Gate to Drain Charge	Q _{gd}			46.5		
Gate Charge Total	Q _g			168		
Gate Plateau Voltage	V _{plateau}			6.5		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _{SD} =57A		0.9	1.1	V
Reverse Recovery Time	t _{rr}	V _R =400V, I _F =57A dI _F /dt=90A/us		227		ns
Reverse Recovery Charge	Q _{rr}			2.2		
Peak Reverse Recovery Current	I _{rrm}			16.2		A

Note:

5. C_{O(er)} is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400V

6. C_{O(tr)} is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400 V



Shenzhen Sanrise Technology Co., LTD

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